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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Farquhar et al.

Examiner: Goff II, John L.

Serial No.: 09/781,730

Art Unit: 1733

Filed: 2/12/01

For: SEMICONDUCTOR DEVICE HAVING A THERMOSET-CONTAINING DIELECTRIC MATERIAL AND METHODS FOR FABRICATING THE SAME

Commissioner for Patents Washington, D.C. 20231

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AMENDMENT

Sir:

In response to the Final Office Action mailed February 4, 2003, please amend the aboveidentified application as follows:

In the Claims:

Claim 23 is amended herein, as marked up in Appendix A. Claims 27-28, 33, 35, 37, 39-43, and 45 have been amended prior to the present office action response. Please cancel claims 27, 30, and 50. Currently pending claims 23-25, 29, 31-33, 35-37, 39-43 and 45-49 for consideration by the Examiner are as follows:

23. (AMENDED) A method for forming a device, comprising the following steps:

providing a fluoropolymer matrix having particles therein;

coating a thermosetting resin on the fluoropolymer matrix;

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